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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

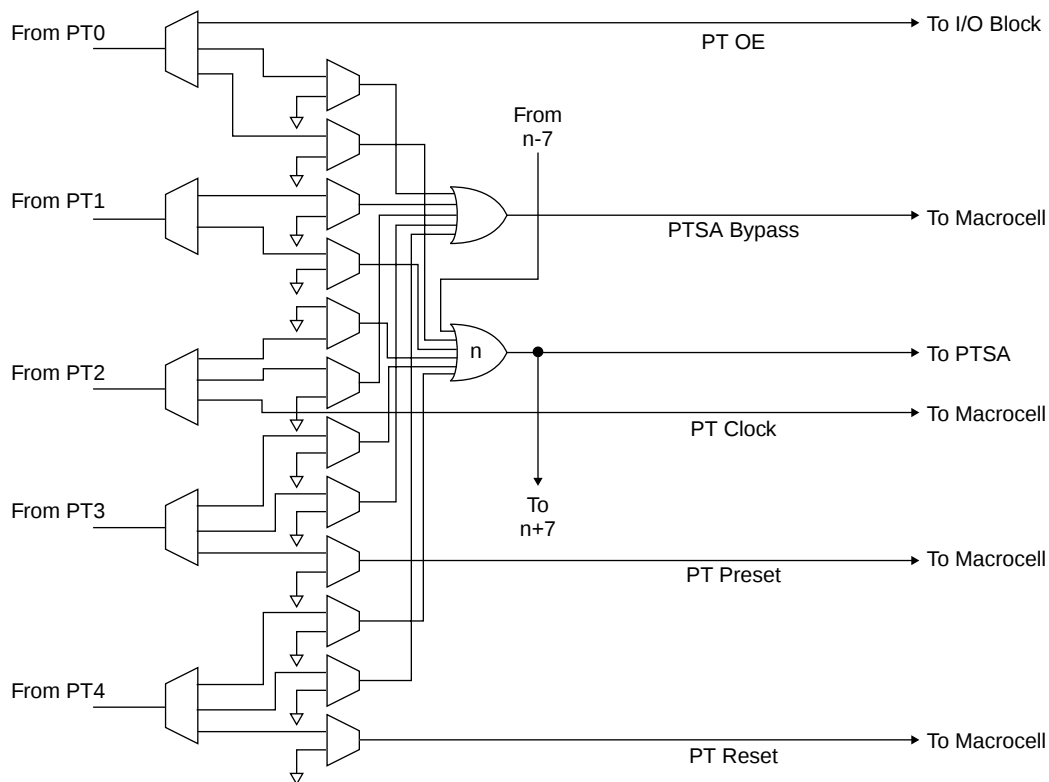
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	32
Number of Macrocells	1024
Number of Gates	-
Number of I/O	304
Operating Temperature	0°C ~ 90°C (TJ)
Mounting Type	Surface Mount
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc51024vg-5f484c

Enhanced Dual-OR Array

To facilitate logic functions requiring a very large number of product terms, the ispMACH 5000VG architecture has been enhanced with an innovative product term expander capability. This capability is embedded in the Dual-OR Array. The Dual-OR Array consists of 64 OR gates. There are two OR gates per macrocell in the GLB. These OR gates are referred to as the Expandable PTSA OR gate and the PTSA-Bypass OR gate.

The PTSA-Bypass OR gate receives its five inputs from the combination of product terms associated with the product term cluster. The PTSA-Bypass OR gate feeds the macrocell directly for fast narrow logic. The Expandable PTSA OR gate receives five inputs from the combination of product terms associated with the product term cluster. It also receives an additional input from the Expanded PTSA OR gate of the N-7 macrocell, where N is the number of the macrocell associated with the current OR gate. The Expandable PTSA OR gate feeds the PTSA for sharing with other product terms and the N+7 Expandable PTSA OR gate. This allows cascading of multiple OR gates for wide functions. There is a small timing adder for each level of expansion. Figure 5 is a graphical representation of the Enhanced Dual-OR Array.

Figure 5. Enhanced Dual-OR Array

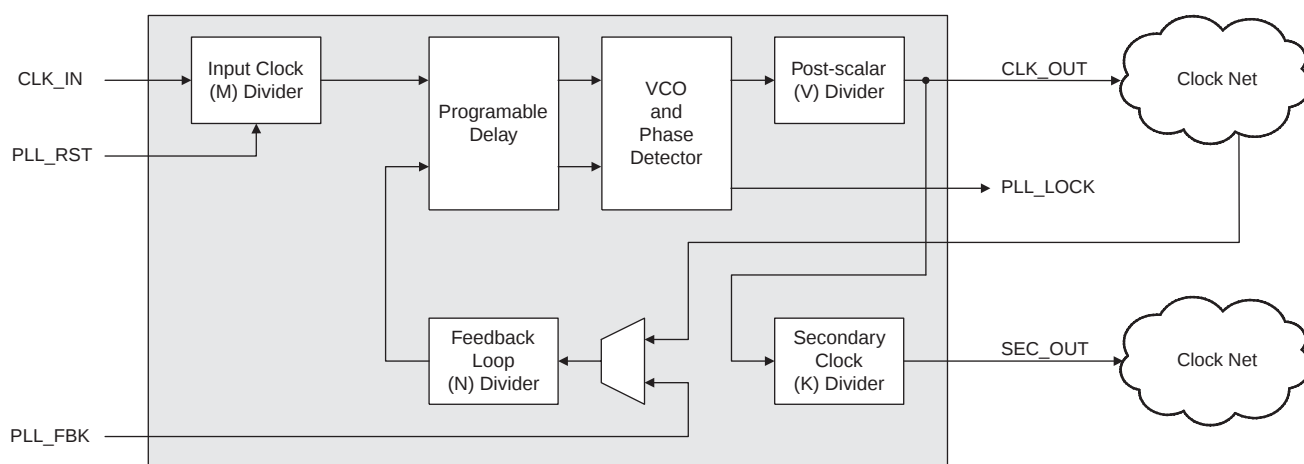


sysCLOCK PLL

The sysCLOCK PLL circuitry consists of Phase-Lock Loops (PLLs) and the various dividers, reset and feedback signals associated with the PLLs. This feature gives the user the ability to synthesize clock frequencies and generate multiple clock signals for routing within the device. Furthermore, it can generate clock signals that are deskewed either at the board level or the device level.

The ispMACH 5000VG devices provide two PLL circuits. PLL0 receives its clock inputs from GCLK 0 and provides outputs to CLK 0 (CLK 1 when using the secondary clock). PLL1 operates with signals from GCLK 3 and CLK 3 (CLK 2 when using the secondary clock). The PLL outputs (CLK_OUT) are routed via a dedicated net to a dedicated pad. Further the buffers at these dedicated pads are regular I/O buffers that can select either the I/O macro-cell or the CLK_OUT (CLK_OUT0/CLK_OUT1) signal. The CLK_OUT nets are not routed through the GRP. Additionally, there are two sets of signals used for external control. Each PLL has a set of PLL_RST, PLL_FBK and PLL_LOCK signals. Figure 10 shows the ispMACH 5000VG PLL block diagram.

Figure 10. PLL Block Diagram



In order to facilitate the multiply and divide capabilities of the PLL, each PLL has dividers associated with it: M, N and K. The M divider is used to divide the clock signal, while the N divider is used to multiply the clock signal. The K divider is only used when a secondary clock output is needed. This divider divides the primary clock output and feeds to a separate global clock net. The V divider is used to provide lower frequency output clocks, while maintaining a stable, high frequency output from the PLL's VCO circuit.

The PLL also has a delay feature that allows the output clock to be advanced or delayed to improve set-up and clock-to-out times for better performance. This operates by inserting delay on the input or feedback lines in 0.5ns increments from 0 to 3.5ns. For more information on the PLL, please refer to Technical Note TN1003: *ispMACH 5000VG PLL Usage Guidelines*.

Power Management

The ispMACH 5000VG devices provide unique power management controls. The devices have two power settings, high power and low power, on a per node basis. Low power consumption is approximately 50% of high power consumption with a timing delay adder (tLP) to the routing delay of the low power node. Each node can be configured as either high power or low power. However, care should be taken when sharing product terms between nodes with different power settings.

The ispMACH 5000VG devices also have a power-off feature for unused product terms. By default, any product term that is not used is configured as such. This allows the device to operate at minimal power consumption without affecting the timing of the design. For more information on power management, please refer to Technical Note TN1002: *Power Estimation in ispMACH 5000VG Devices*.

IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 5000VG devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port has its own supply voltage and can operate with LVCMOS3.3, 2.5 and 1.8V standards.

sysIO Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os' physical nature should be minimal so that board test time is minimized. The ispMACH 5000VG family of devices allows this by offering the user the ability to quickly configure the physical nature of the sysIO cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM™ System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

IEEE 1532-Compliant In-System Programming

In-system programming of devices provides a number of significant benefits including rapid prototyping, lower inventory levels, higher quality and the ability to make in-field modifications. All ispMACH 5000VG devices provide In-System Programming (ISP™) capability through their Boundary Scan Test Access Port. This capability has been implemented in a manner that ensures that the port remains compliant to the IEEE 1532 standard. By using IEEE 1532 as the communication interface through which ISP is achieved, customers get the benefit of a standard, well-defined interface.

The ispMACH 5000VG devices can be programmed across the commercial temperature and voltage range. The PC-based Lattice software facilitates in-system programming of ispMACH 5000VG devices. The software takes the JEDEC file output produced by the design implementation software, along with information about the scan chain, and creates a set of vectors used to drive the scan chain. The software can use these vectors to drive a scan chain via the parallel port of a PC. Alternatively, the software can output files in formats understood by common automated test equipment. This equipment can then be used to program ispMACH 5000VG devices during the testing of a circuit board.

Security Bit

A programmable security bit is provided on the ispMACH 5000VG devices as a deterrent to unauthorized copying of the array configuration patterns. Once programmed, this bit prevents readback of the programmed pattern by a device programmer, securing proprietary design from competitors. The security bit also prevents programming and verification. The entire device must be erased in order to erase the security bit.

Hot Socketing

The ispMACH 5000VG devices are well suited for those applications that require hot socketing capability. Hot socketing a device requires that the device, when powered down, can tolerate active signals on the I/Os and inputs without being damaged. Additionally, it requires that the effects of the powered-down device be minimal on active signals.

Density Migration

The ispMACH 5000 family has been designed to ensure that different density devices in the same package have the same pin-out. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is possible to shift a lower utilization design targeted for a high density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
I _{IL} , I _{IH} ¹	Input or I/O Leakage Current	0V ≤ V _{IN} ≤ V _{IH} (MAX)	—	—	+/-10	μA
I _{PU} ²	I/O Weak Pull-up Resistor Current	V _{CCO} = 3.3	-30	—	-150	μA
		V _{CCO} = 2.5	-20	—	-150	μA
		V _{CCO} = 1.8	-10	—	-150	μA
I _{PD} ²	I/O Weak Pull-down Resistor Current	V _{IL} (MAX) ≤ V _{IN} ≤ V _{IH} (MAX)	30	—	150	μA
I _{BHLS} ²	Bus Hold Low Sustaining Current	V _{IN} = V _{IL} (MAX)	30	—	—	μA
I _{BHHS} ²	Bus Hold High Sustaining Current	V _{CCO} = 3.3	-30	—	—	μA
		V _{CCO} = 2.5	-20	—	—	μA
		V _{CCO} = 1.8	-10	—	—	μA
I _{BHLO} ²	Bus Hold Low Overdrive Current	0V ≤ V _{IN} ≤ V _{IH} (MAX)	—	—	150	μA
I _{BHHO} ²	Bus Hold High Overdrive Current	0V ≤ V _{IN} ≤ V _{IH} (MAX)	—	—	-150	μA
I _{CC} ^{3, 4, 5}	Operating Power Supply Current	V _{CC} = 3.3V	—	380	—	mA
V _{BHT}	Bus Hold Trip Points		V _{IL} (MAX)	—	V _{IH} (MIN)	V
C ₁	I/O Capacitance ³	V _{CC} = 3.3V, V _{IO} = 0 to V _{IH} (MAX)	—	10	—	pf
		V _{CCO} = 3.3V, 2.5, 1.8, 1.5				
C ₂	Clock Capacitance ³	V _{CC} = 3.3V, V _{IO} = 0 to V _{IH} (MAX)	—	10	—	pf
		V _{CCO} = 3.3V, 2.5, 1.8, 1.5				
C ₃	Global Input Capacitance ³	V _{CC} = 3.3V, V _{IO} = 0 to V _{IH} (MAX)	—	10	—	pf
		V _{CCO} = 3.3V, 2.5, 1.8, 1.5				

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.

2. Only available for LVCMOS and LVTTL standards.

3. $T_A = 25^\circ C$, $f = 1.0MHz$.

4. Device configured with 16-bit counters.

5. I_{CC} varies with specific device configuration and operating frequency.

ispMACH 5768VG External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description ^{1,2,3}	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
t_{PD}	Data propagation delay, 5-PT bypass	—	5.0	—	7.5	—	10.0	—	12.0	ns
t_{PD_PTSA}	Data propagation delay, intrasegment path	—	6.0	—	9.0	—	11.5	—	13.5	ns
t_{PD_GLOBAL}	Data propagation delay, intersegment path	—	6.5	—	9.75	—	13.0	—	16.0	ns
t_S	GLB register setup time before clock, 5-PT bypass	3.0	—	5.0	—	7.5	—	9.3	—	ns
t_{S_PTSA}	GLB register setup time before clock	3.0	—	6.0	—	8.5	—	10.0	—	ns
t_{SIR}	GLB register setup time before clock, input register path	2.8	—	3.0	—	4.0	—	5.0	—	ns
t_H	GLB register hold time before clock, 5-PT bypass	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{H_PTSA}	GLB register hold time before clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{HIR}	GLB register hold time before clock, input reg. path	0.0	—	0.0	—	0.0	—	0.0	—	ns
t_{CO}	GLB register clock-to-output delay	—	4.4	—	5.0	—	6.0	—	7.0	ns
t_R	External reset pin to output delay	—	6.5	—	9.0	—	10.0	—	10.9	ns
t_{RW}	External reset pulse duration	4.0	—	6.0	—	8.0	—	9.5	—	ns
$t_{LPTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	9.75	—	11.5	—	13.4	ns
$t_{SPTOE/DIS}$	Input to output segment product term output enable/disable	—	8.0	—	11.25	—	17.5	—	20.4	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	6.2	—	7.5	—	8.85	—	10.0	ns
t_{CW}	Global clock width, high or low	1.6	—	2.75	—	3.6	—	4.3	—	ns
t_{GW}	Global gate width low (for low transparent) or high (for high transparent)	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{WIR}	Input register clock width, high or low	1.8	—	2.75	—	3.6	—	4.3	—	ns
t_{SKEW}	Clock-to-out skew, block level	—	0.25	—	0.35	—	0.45	—	0.55	ns
	Clock-to-out skew, segment level	—	0.4	—	0.5	—	0.6	—	0.7	ns
f_{MAX}^4	Clock frequency with internal feedback	178.6	—	117.0	—	87.0	—	73.0	—	MHz
$f_{MAX} (Ext.)$	Clock frequency with external feedback, $1/(t_{S_PTSA} + t_{CO})$	135.1	—	90.9	—	69.0	—	58.8	—	MHz
$f_{MAX} (Tog.)$	Clock frequency max Toggle	312.5	—	181.0	—	138.0	—	116.0	—	MHz

Timing v.1.20

1. Timing numbers are based on default LVCMOS 3.3 I/O Buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, assuming segment and global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using SRP feedback.

ispMACH 5768VG Internal Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5		-75		-10		-12		Units
		Min	Max	Min	Max	Min	Max	Min	Max	
In/Out Delays										
t _{IN}	Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t _{GCLK_IN}	Global Clock Input Buffer Delay	—	0.65	—	0.95	—	1.25	—	1.40	ns
t _{GOE}	Global OE Pin Delay	—	4.05	—	5.00	—	6.00	—	7.00	ns
t _{BUF}	Delay through Output Buffer	—	1.15	—	1.50	—	1.75	—	1.90	ns
t _{EN}	Output Enable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t _{DIS}	Output Disable Time	—	2.15	—	2.50	—	2.85	—	3.00	ns
t _{RSTb}	Global RESETbar Pin Delay	—	4.60	—	6.50	—	7.00	—	7.50	ns
Routing Delays										
t _{ROUTE}	Delay through SRP	—	2.80	—	4.20	—	5.65	—	6.90	ns
t _{PTSA}	Product Term Sharing Array Delay	—	0.40	—	1.85	—	2.35	—	2.50	ns
t _{PDB}	5-PT Bypass Propagation Delay	—	0.40	—	0.85	—	1.35	—	1.80	ns
t _{PDi}	Macrocell Propagation Delay	—	1.00	—	0.50	—	0.50	—	0.80	ns
t _{INREG}	Input Buffer to Macrocell Register Delay	—	3.00	—	3.05	—	3.50	—	4.40	ns
t _{FBK}	Internal Feedback Delay	—	0.00	—	0.00	—	0.00	—	0.00	ns
t _{GCLK}	Global Clock Tree Delay	—	0.85	—	0.70	—	0.55	—	0.65	ns
t _{PLL_DELAY}	Programmable PLL Delay Increment	—	0.50	—	0.50	—	0.50	—	0.50	ns
t _{PLL_SEC_DELAY}	Additional Delay When Using Secondary PLL Output	—	0.60	—	0.60	—	0.60	—	0.60	ns
t _{GRP}	Global Routing Pool Delay	—	1.50	—	2.25	—	3.00	—	4.00	ns
Register/Latch Delays										
t _S	D-Register Setup Time	0.65	—	0.65	—	1.05	—	1.25	—	ns
t _{S_PT}	D-Register Setup Time with PT Clock	0.65	—	0.65	—	1.05	—	1.25	—	ns
t _H	D-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t _{ST}	T-Register Setup Time	1.15	—	1.15	—	1.55	—	1.75	—	ns
t _{ST_PT}	T-Register Setup Time with PT Clock	1.15	—	1.15	—	1.55	—	1.75	—	ns
t _{HT}	T-Register Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t _{COi}	Register Clock to Output/Feedback MUX Time	—	1.75	—	1.85	—	2.45	—	3.05	ns
t _{CES}	Clock Enable Setup Time	2.60	—	3.90	—	5.05	—	5.95	—	ns
t _{CEH}	Clock Enable Hold Time	0.60	—	0.90	—	1.20	—	1.45	—	ns
t _{SL}	Latch Setup Time	2.80	—	4.20	—	5.50	—	6.60	—	ns
t _{SL_PT}	Latch Setup Time with PT Clock	2.80	—	4.20	—	5.50	—	6.60	—	ns
t _{HL}	Latch Hold Time	0.00	—	0.00	—	0.00	—	0.00	—	ns
t _{GOi}	Latch Gate to Output/Feedback MUX Time	—	1.75	—	2.50	—	3.50	—	4.50	ns
t _{PDLi}	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	2.40	—	3.50	—	4.00	—	4.50	ns
t _{SRI}	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.75	—	1.00	—	1.25	—	1.50	ns
t _{SRR}	Asynchronous Reset or Set Recovery Delay	—	1.00	—	1.50	—	2.00	—	2.50	ns
Control Delays										
t _{BCLK}	GLB PT Clock Delay	—	3.10	—	4.65	—	6.00	—	7.00	ns
t _{PTCLK}	Macrocell PT Clock Delay	—	3.00	—	4.50	—	6.00	—	7.00	ns

ispMACH 5768VG Timing Adders

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{BLA}	t_{ROUTE}	GLB Loading Adder	—	0.0	—	0.0	—	0.0	—	0.0	ns
t_{EXP}	t_{PTSA}	PT Expander Adder	—	1.5	—	2.0	—	2.5	—	2.5	ns
t_{LP}	t_{ROUTE}	Low Power Adder	—	1.5	—	1.5	—	1.5	—	1.5	ns
t_{IOI} Input Adders											
LVC MOS18_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using LVC MOS1.8 standard	—	0.90	—	0.90	—	0.90	—	0.90	ns
LVC MOS25_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using LVC MOS2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
LVC MOS33_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using LVC MOS3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using LVTTL standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using PCI_X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using SSTL3_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL3_II_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using SSTL3_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_I_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using SSTL2_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_II_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using SSTL2_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
CTT33_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using CTT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using CTT2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
HSTL_I_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using HSTL_I standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
HSTL_III_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using HSTL_III standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
GTL+_in	$t_{IN}, t_{GCLK_IN}, t_{RSTb}, t_{GOE}$	Using GTL+ standard	—	1.50	—	1.50	—	1.50	—	1.50	ns
LVDS_in	t_{GCLK_IN}	Using LVDS standard	—	1.70	—	1.70	—	1.70	—	1.70	ns
LVPECL_in	t_{GCLK_IN}	Using LVPECL standard	—	2.10	—	2.10	—	2.10	—	2.10	ns
t_{IOO} Output Adders											
LVC MOS18_4mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 4mA Buffer	—	3.00	—	3.00	—	3.00	—	3.00	ns
LVC MOS18_5mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 5.33mA Buffer	—	2.50	—	2.50	—	2.50	—	2.50	ns
LVC MOS18_8mA_out	t_{BUF}, t_{EN}, t_{DIS}	Output configured as 1.8V & 8mA Buffer	—	1.85	—	1.85	—	1.85	—	1.85	ns

Note: Open drain timing is the same as corresponding LVC MOS timing.

Timing v.1.20

ispMACH 5768VG Timing Adders (Continued)

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
HSTL_III_out	t_{BUF} , t_{EN} , t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF} , t_{EN} , t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.20

ispMACH 51024VG Timing Adders

Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{BLA}	t_{ROUTE}	GLB Loading Adder	—	0.0	—	0.0	—	0.0	—	0.0	ns
t_{EXP}	t_{PTSA}	PT Expander Adder	—	1.5	—	2.0	—	2.5	—	2.5	ns
t_{LP}	t_{ROUTE}	Low Power Adder	—	1.5	—	1.5	—	1.5	—	1.5	ns
t_{OI} Input Adders											
LVCMOS18_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using LVCMOS1.8 standard	—	0.90	—	0.90	—	0.90	—	0.90	ns
LVCMOS25_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using LVCMOS2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
LVCMOS33_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using LVCMOS3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
LVTTL	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using LVTTL standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using PCI standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
PCI_X_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using PCI_X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
AGP_1X_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using AGP-1X standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL3_I_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using SSTL3_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL3_II_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using SSTL3_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_I_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using SSTL2_I standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
SSTL2_II_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using SSTL2_II standard	—	1.00	—	1.00	—	1.00	—	1.00	ns
CTT33_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using CTT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using CTT2.5 standard	—	0.15	—	0.15	—	0.15	—	0.15	ns
HSTL_I_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using HSTL_I standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
HSTL_III_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using HSTL_III standard	—	1.25	—	1.25	—	1.25	—	1.25	ns
GTL+_in	t_{IN} , t_{GCLK_IN} , t_{RSTb} , t_{GOE}	Using GTL+ standard	—	1.50	—	1.50	—	1.50	—	1.50	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

ispMACH 51024VG Timing Adders (Continued)

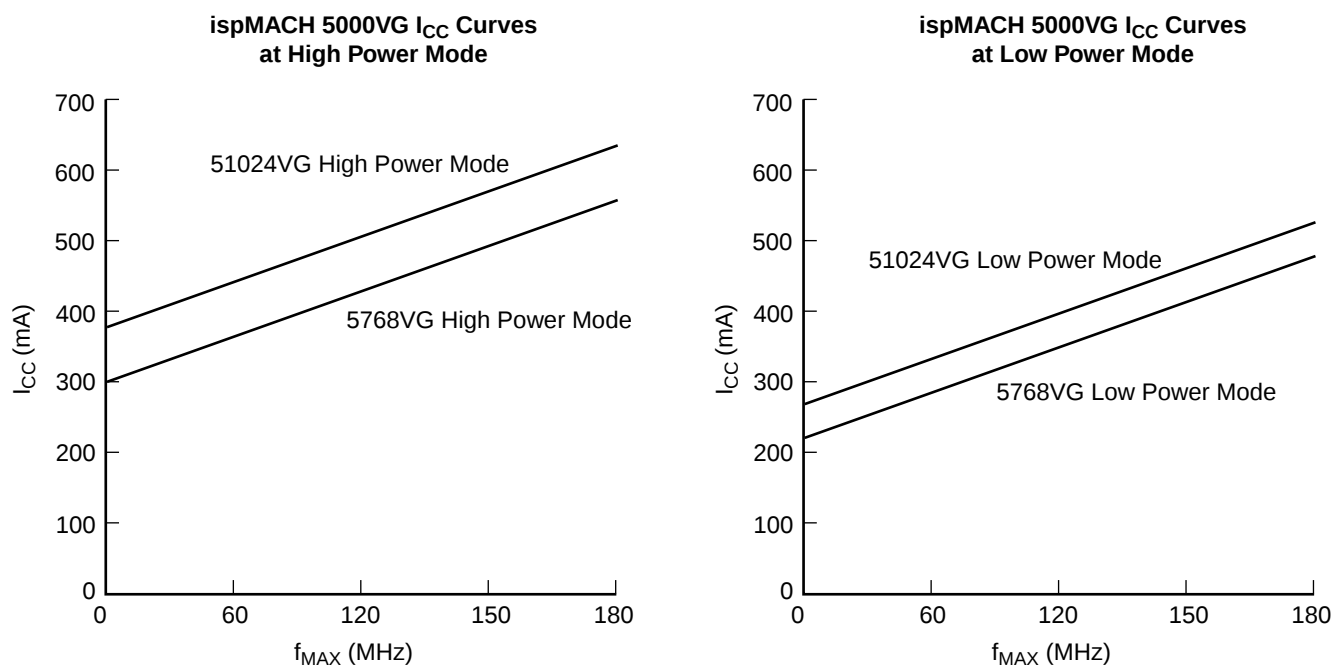
Adder Type	Base Parameter	Description	-5		-75		-10		-12		Units
			Min	Max	Min	Max	Min	Max	Min	Max	
SSTL2_I_out	t_{BUF} t_{EN} , t_{DIS}	Using SSTL2_I standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
SSTL2_II_out	t_{BUF} t_{EN} , t_{DIS}	Using SSTL2_II standard	—	-0.25	—	-0.25	—	-0.25	—	-0.25	ns
CTT33_out	t_{BUF} t_{EN} , t_{DIS}	Using CCT3.3 standard	—	0.0	—	0.0	—	0.0	—	0.0	ns
CTT25_out	t_{BUF} t_{EN} , t_{DIS}	Using CCT2.5 standard	—	0.25	—	0.25	—	0.25	—	0.25	ns
HSTL_I_out	t_{BUF} t_{EN} , t_{DIS}	Using HSTL_I standard	—	-0.30	—	-0.30	—	-0.30	—	-0.30	ns
HSTL_III_out	t_{BUF} t_{EN} , t_{DIS}	Using HSTL_III standard	—	0.00	—	0.00	—	0.00	—	0.00	ns
GTL+_out	t_{BUF} t_{EN} , t_{DIS}	Using GTL+ standard	—	0.30	—	0.30	—	0.30	—	0.30	ns

Note: Open drain timing is the same as corresponding LVCMOS timing.

Timing v.1.10

Power Consumption

ispMACH 5000VG Typical Power vs. Frequency



Note: The devices are configured with maximum number of 16-bit counters, no PLL, typical current at 3.3V, 25° C.

Power Estimation Coefficients

Device	K0	K1	K2	K3	K4	K5	K6	I_{DC} (mA)	I_{DCO} (mA)
ispMACH 5768VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	65	20
ispMACH 51024VG	0.0014	0.0014	0.054	1.5	0.152	0.105	5.0	80	20

Note: For further information about the use of these coefficients, refer to Technical Note TN1002, *Power Estimation in ispMACH 5000VG Devices*.

K0 = average current per product term in high power/MHz

K1 = average current per product term in low power/MHz

K2 = average current per GRP line/MHz

K3 = average current per PLL/MHz

K4 = DC current per product terms in high power

K5 = DC current per product terms in low power

K6 = Static DC current per PLL

I_{DC} = Static device current with all product terms powered off

I_{DCO} = Static I/O bank current

I_{CC} estimates are based on typical conditions ($V_{CC} = 3.3V$, room temperature) and an assumption of one GLB load on average exists. These values are for estimates only. Since the value of I_{CC} is sensitive to operating conditions and the program in the device, the actual I_{CC} should be verified.

ispMACH 5768VG Power Supply and NC Connections¹

Signal	256-Ball fpBGA ²	484-Ball fpBGA ²
V _{CC}	F8, F9, H6, H11, J6, J11, L8, L9	B17, B2, B21, B6, C14, C9, E18, E5, F2, F21, J20, J3, P20, P3, U2, U21, Y14, Y9, AA17, AA2, AA21, AA6
V _{CCO0}	C3, C7, G3	B5, D7, E2, E6, E9, F5, G4, J5
V _{CCO1}	K3, P3, P7	P5, U5, V6, V9, Y3
V _{CCO2}	K14, P10, P14	P18, U18, V14, V17, Y20
V _{CCO3}	C10, C14, G14	B18, D16, E14, E17, E21, F18, G19, J18
V _{CCP0}	H1	L7
V _{CCP1}	H16	N18
V _{CCJ}	J1	P4
V _{REF0}	E7	A9
V _{REF1}	M7	AA10
V _{REF2}	R13	AA13
V _{REF3}	A8	A15
GND PLL 0	H7	L6
GND PLL 1	J10	L16
GND	A1, C5, C12, E3, E14, G7, G8, G9, G10, H8, H9, H10, J7, J8, J9, K7, K8, K9, K10, M3, M14, P5, P12	A1, A22, C3, C20, D4, D19, E7, E16, G5, G7, G8, G9, G10, G11, G12, G13, G14, G15, G16, G18, H7, H8, H9, H10, H11, H12, H13, H14, H15, H16, J7, J8, J9, J10, J11, J12, J13, J14, J15, J16, K7, K8, K9, K10, K11, K12, K13, K14, K15, K16, L8, L9, L10, L11, L12, L13, L14, L15, M7, M8, M9, M10, M11, M12, M13, M14, M15, M16, N7, N8, N9, N10, N11, N12, N13, N14, N15, N16, P7, P8, P9, P10, P11, P12, P13, P14, P15, P16, R7, R8, R9, R10, R11, R12, R13, R14, R15, R16, T4, T7, T8, T9, T10, T11, T12, T13, T14, T15, T16, T19, W7, W16, AB1, AB22
NC ³	—	AA1

1. All grounds must be electrically connected at the board level.

2. Not all grounds internally connected within the device.

3. NC pins are not to be connected to any active signals, VCC or GND.

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
3	4B-24	G11	M19
3	4B-26	F11	M21
3	4B-28	F10	L19
3	4B-30/CLK_OUT1	B11	L20
3	GNDIO3	GND	GND
3	4A-30	NC	M17
3	4A-28	NC	M22
3	4A-26	NC	K20
3	4A-24	NC	L18
3	4A-22	NC	L21
3	4A-20	NC	K19
3	4A-18	NC	L22
3	4A-16	NC	K17
3	4A-14	E13	K22
3	4A-12	B12	L17
3	GNDIO3	GND	GND
3	4A-10	E15	K21
3	4A-8	D15	K18
3	4A-6	NC	J17
3	4A-4	NC	J19
3	4A-2	D16	J22
3	4A-0	E12	J21
3	5B-0	NC	H19
3	5B-2	NC	H20
3	5B-4	NC	H17
3	5B-6	NC	H18
3	5B-8	NC	H22
3	5B-10	NC	H21
3	GNDIO3	GND	GND
3	5B-12	NC	G20
3	5B-14	NC	G22
3	5B-16	NC	G17
3	5B-18	NC	G21
3	5B-20	NC	F19
3	5B-22	NC	F20
3	5B-24	A16	F22
3	5B-26	B15	E22
3	5B-28	A15	E19
3	5B-30	D13	E20
3	5A-30	B14	D22
3	5A-28	B16	D21
3	GNDIO3	GND	GND
3	5A-26	C16	D20

Bank No.	Signal	256 fpBGA	484 fpBGA
3	5A-24	C15	C22
3	5A-22	D14	C18
3	5A-20	A14	C19
3	5A-18	C13	D17
3	5A-16	B13	C21
3	5A-14	NC	NC
3	5A-12	NC	NC
3	GNDIO3	GND	GND
3	5A-10	NC	NC
3	5A-8	NC	NC
3	5A-6	NC	B22
3	5A-4	NC	D18
3	5A-2	NC	B20
3	5A-0	NC	F17
3	5D-0	NC	B19
3	5D-2	NC	C17
3	GNDIO3	GND	GND
3	5D-4	NC	A21
3	5D-6	NC	D15
3	5D-8	NC	A20
3	5D-10	NC	C16
3	5D-12	NC	A19
3	5D-14	NC	F16
3	5D-16	NC	B16
3	5D-18	NC	D14
3	5D-20	NC	A18
3	5D-22	A13	F15
3	5D-24	A12	A17
3	5D-26	A11	B15
3	GNDIO3	GND	GND
3	5D-28	A10	A16
3	5D-30	C11	F14
3	5C-0	A9	C15
3	5C-2	D12	D13
3	5C-4	D11	E15
3	5C-6	B10	F13
3	5C-8	B9	B14
3	5C-10	E11	E13
3	5C-12/VREF3	A8	A15
3	5C-14	D10	D12
3	5C-16	E10	A14
3	5C-18	A7	B13
3	GNDIO3	GND	GND

ispMACH 5768VG Logic Signal Connections (Continued)

Bank No.	Signal	256 fpBGA	484 fpBGA
3	5C-20	C9	A13
3	5C-22	E9	B12
3	5C-24	D9	C13
3	5C-26	B8	A12
3	5C-28	A6	C12
3	5C-30	B7	A11
—	GCLK0	H4	P6
—	GCLK1	J4	R6
—	GCLK2	H14	P17
—	GCLK3	H13	P19
—	GOE0	J15	R18
—	GOE1	H15	R17
—	RESETB	J14	R19
—	TCK	J3	R3
—	TDI	H3	R2
—	TDO	J2	R4
—	TMS	H2	T1
—	TOE	J13	T18

ispMACH 51024VG Logic Signal Connections

Bank No.	Signal	484 fpBGA	676 fpBGA
0	0C-30	D11	A13
0	0C-28	B11	B13
0	0C-26	E12	A12
0	0C-24	C11	B12
0	0C-22	F12	C12
0	0C-20	B10	A11
0	GNDIO0	GND	GND
0	0C-18	A10	B11
0	0C-16	D10	A10
0	0C-14/VREF0	A9	C11
0	0C-12	E11	E12
0	0C-10	B9	B10
0	0C-8	F11	D11
0	0C-6	A8	A9
0	0C-4	C10	C10
0	0C-2	A7	B9
0	0C-0	E10	A8
0	0D-30	B8	C9
0	0D-28	C8	B8
0	GNDIO0	GND	GND
0	0D-26	F10	E10
0	0D-24	A6	A7
0	0D-22	F9	D9
0	0D-20	C7	C8
0	0D-18	D9	B7
0	0D-16	B7	A6
0	0D-14	E8	C7
0	0D-12	A5	B6
0	0D-10	F8	A5
0	0D-8	C6	C6
0	0D-6	D8	D7
0	0D-4	A3	E8
0	GNDIO0	GND	GND
0	0D-2	A2	B5
0	0D-0	A4	A4
0	0A-0	F7	A3
0	0A-2	C5	B4
0	0A-4	F6	C5
0	0A-6	B3	F8
0	0A-8	NC	A2
0	0A-10	NC	B3
0	GNDIO0	GND	GND
0	0A-12	NC	C4

Bank No.	Signal	484 fpBGA	676 fpBGA
0	0A-14	NC	D5
0	0A-16	B4	E6
0	0A-18	D5	D4
0	0A-20	B1	B1
0	0A-22	D6	C2
0	0A-24	C4	F6
0	0A-26	E4	D3
0	GNDIO0	GND	GND
0	0A-28	C2	E4
0	0A-30	C1	F5
0	0B-30	D1	C1
0	0B-28	D2	D2
0	0B-26	D3	E3
0	0B-24	E1	D1
0	0B-22	E3	E2
0	0B-20	F4	H6
0	0B-18	F1	F3
0	0B-16	F3	E1
0	0B-14	G6	G4
0	0B-12	G1	F2
0	GNDIO0	GND	GND
0	0B-10	G2	H5
0	0B-8	H1	G3
0	0B-6	G3	F1
0	0B-4	H2	G2
0	0B-2	H5	H3
0	0B-0	H6	G1
0	1A-0	J1	H2
0	1A-2	K1	J4
0	1A-4	H3	H1
0	1A-6	J2	J3
0	1A-8	H4	K5
0	1A-10	K2	J2
0	GNDIO0	GND	GND
0	1A-12	J6	J1
0	1A-14	L1	K3
0	1A-16	K3	K2
0	1A-18	J4	K1
0	1A-20	L2	L4
0	1A-22	M1	L3
0	1A-24	K6	L2
0	1A-26	K4	M5
0	1A-28	L3	L1

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
0	1A-30	K5	M3
0	GNDIO0	GND	GND
0	1B-30/CLK_OUT0	N1	M2
0	1B-28	M2	M1
0	1B-26	P1	N6
0	1B-24	L4	N5
0	1B-22	N2	N4
0	1B-20	M3	N3
0	1B-18	L5	N2
0	1B-16	R1	N1
0	1B-14	P2	P6
0	1B-12	N3	P4
0	GNDIO0	GND	GND
0	1B-10	M6	P3
0	1B-8	M5	P2
0	1B-6/PLL_RST0	M4	P1
0	1B-4/PLL_FBK0	N4	R4
0	1B-2	N6	R3
0	1B-0	N5	R2
1	2B-0	NC	R1
1	2B-2	NC	T1
1	2B-4	NC	T3
1	2B-6	NC	T2
1	2B-8	NC	U1
1	2B-10	NC	U2
1	GNDIO1	GND	GND
1	2B-12	NC	U3
1	2B-14	NC	U4
1	2B-16	NC	V1
1	2B-18	NC	V2
1	2B-20	NC	V3
1	2B-22	NC	V4
1	2B-24	NC	W1
1	2B-26	NC	V6
1	2B-28	NC	W2
1	2B-30	NC	W3
1	GNDIO1	GND	GND
1	2A-30	NC	Y1
1	2A-28	NC	W5
1	2A-26	NC	Y2
1	2A-24	NC	Y3
1	2A-22	NC	AA1
1	2A-20	NC	Y4

Bank No.	Signal	484 fpBGA	676 fpBGA
1	2A-18	NC	AA2
1	2A-16	NC	AA3
1	2A-14	NC	AB1
1	2A-12	NC	AB2
1	GNDIO1	GND	GND
1	2A-10	NC	AA5
1	2A-8	NC	AB3
1	2A-6	NC	AC1
1	2A-4	NC	AB4
1	2A-2	NC	AC2
1	2A-0	NC	AD1
1	3B-0	R5	AC3
1	3B-2	T2	AD2
1	3B-4	T5	AE1
1	3B-6	T3	AD3
1	3B-8	U1	AE2
1	3B-10	U4	AC5
1	GNDIO1	GND	GND
1	3B-12	V1	AF1
1	3B-14	U3	AD4
1	3B-16	V5	AE3
1	3B-18	V2	AC6
1	3B-20	W1	AF2
1	3B-22	V3	AG1
1	3B-24	W2	AF3
1	3B-26	Y1	AG2
1	3B-28	Y2	AH1
1	3B-30	W3	AE5
1	3A-30	AA3	AF4
1	3A-28	W4	AG3
1	GNDIO1	GND	GND
1	3A-26	W5	AE6
1	3A-24	Y4	AH2
1	3A-22	T6	AJ1
1	3A-20	Y5	AG4
1	3A-18	U6	AF6
1	3A-16	AA4	AG5
1	3A-14	NC	AH4
1	3A-12	NC	AJ3
1	GNDIO1	GND	GND
1	3A-10	NC	AK2
1	3A-8	NC	AE8
1	3A-6	W6	AH5

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
1	3A-4	V4	AJ4
1	3A-2	U7	AK3
1	3A-0	AB2	AK4
1	3D-0	V7	AJ5
1	3D-2	AA5	AH6
1	GNDIO1	GND	GND
1	3D-4	AB3	AF8
1	3D-6	Y6	AG7
1	3D-8	AB4	AK5
1	3D-10	Y7	AJ6
1	3D-12	AB5	AH7
1	3D-14	V8	AK6
1	3D-16	AA7	AJ7
1	3D-18	Y8	AH8
1	3D-20	AB6	AG9
1	3D-22	W8	AK7
1	3D-24	AA8	AF10
1	3D-26	Y10	AJ8
1	GNDIO1	GND	GND
1	3D-28	U8	AH9
1	3D-30	AB7	AK8
1	3C-0	U9	AJ9
1	3C-2	AA9	AH10
1	3C-4	W9	AK9
1	3C-6	AB8	AG11
1	3C-8	U10	AJ10
1	3C-10	AB9	AF12
1	3C-12	V11	AH11
1	3C-14/VREF1	AA10	AK10
1	3C-16	V10	AJ11
1	3C-18	AB10	AK11
1	GNDIO1	GND	GND
1	3C-20	W10	AH12
1	3C-22	W11	AJ12
1	3C-24	U11	AK12
1	3C-26	AA11	AH13
1	3C-28	V12	AJ13
1	3C-30	AB11	AK13
2	4C-30	W12	AK18
2	4C-28	Y11	AK19
2	4C-26	Y12	AJ19
2	4C-24	AB12	AH19
2	4C-22	U12	AK20

Bank No.	Signal	484 fpBGA	676 fpBGA
2	4C-20	AA12	AJ20
2	GNDIO2	GND	GND
2	4C-18	Y13	AK21
2	4C-16	AB13	AH20
2	4C-14	W13	AF19
2	4C-12/VREF2	AA13	AJ21
2	4C-10	U13	AG20
2	4C-8	AB14	AK22
2	4C-6	V13	AH21
2	4C-4	AA14	AJ22
2	4C-2	U14	AK23
2	4C-0	AB15	AH22
2	4D-30	Y15	AJ23
2	4D-28	AB16	AK24
2	GNDIO2	GND	GND
2	4D-26	AA15	AF21
2	4D-24	W14	AG22
2	4D-22	AB17	AH23
2	4D-20	Y16	AJ24
2	4D-18	AA16	AK25
2	4D-16	Y17	AH24
2	4D-14	AB18	AJ25
2	4D-12	V15	AK26
2	4D-10	AB19	AJ26
2	4D-8	W15	AH25
2	4D-6	AB20	AG24
2	4D-4	AA18	AF23
2	GNDIO2	GND	GND
2	4D-2	U15	AK27
2	4D-0	W17	AK28
2	4A-0	U16	AJ27
2	4A-2	AA19	AH26
2	4A-4	V16	AE23
2	4A-6	AB21	AK29
2	4A-8	NC	AJ28
2	4A-10	NC	AH27
2	GNDIO2	GND	GND
2	4A-12	NC	AG26
2	4A-14	NC	AF25
2	4A-16	Y18	AJ29
2	4A-18	W18	AG27
2	4A-20	AA20	AJ30
2	4A-22	W19	AH29

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
2	4A-24	Y19	AE25
2	4A-26	V19	AG28
2	GNDIO2	GND	GND
2	4A-28	Y21	AF27
2	4A-30	W20	AE26
2	4B-30	AA22	AH30
2	4B-28	W21	AG29
2	4B-26	Y22	AF28
2	4B-24	V20	AG30
2	4B-22	V21	AF29
2	4B-20	W22	AC25
2	4B-18	V18	AE28
2	4B-16	U20	AF30
2	4B-14	V22	AD27
2	4B-12	U19	AE29
2	GNDIO2	GND	GND
2	4B-10	U17	AC26
2	4B-8	U22	AD28
2	4B-6	T20	AE30
2	4B-4	T21	AD29
2	4B-2	T17	AC28
2	4B-0	R20	AD30
2	5A-0	NC	AC29
2	5A-2	NC	AB27
2	5A-4	NC	AC30
2	5A-6	NC	AB28
2	5A-8	NC	AA26
2	5A-10	NC	AB29
2	GNDIO2	GND	GND
2	5A-12	NC	AB30
2	5A-14	NC	AA28
2	5A-16	NC	AA29
2	5A-18	NC	AA30
2	5A-20	NC	Y27
2	5A-22	NC	Y28
2	5A-24	NC	Y29
2	5A-26	NC	W26
2	5A-28	NC	Y30
2	5A-30	NC	W28
2	GNDIO2	GND	GND
2	5B-30	NC	W29
2	5B-28	NC	W30
2	5B-26	NC	V25

Bank No.	Signal	484 fpBGA	676 fpBGA
2	5B-24	NC	V26
2	5B-22	NC	V27
2	5B-20	NC	V28
2	5B-18	NC	V29
2	5B-16	NC	V30
2	5B-14	NC	U25
2	5B-12	NC	U27
2	GNDIO2	GND	GND
2	5B-10	NC	U28
2	5B-8	NC	U29
2	5B-6	NC	U30
2	5B-4	NC	T27
2	5B-2	NC	T28
2	5B-0	NC	T29
3	6B-0	R21	T30
3	6B-2	T22	R29
3	6B4/PLL_FBK1	P21	R27
3	6B6/PLL_RST1	N20	R28
3	6B-8	R22	R30
3	6B-10	N21	P30
3	GNDIO3	GND	GND
3	6B-12	M18	P29
3	6B-14	N19	P28
3	6B-16	P22	P27
3	6B-18	M20	N30
3	6B-20	N22	N29
3	6B-22	N17	N28
3	6B-24	M19	N27
3	6B-26	M21	N25
3	6B-28	L19	M30
3	6B-30/CLK_OUT1	L20	M29
3	GNDIO3	GND	GND
3	6A-30	M17	M28
3	6A-28	M22	L30
3	6A-26	K20	M26
3	6A-24	L18	L29
3	6A-22	L21	L28
3	6A-20	K19	L27
3	6A-18	L22	K30
3	6A-16	K17	K29
3	6A-14	K22	K28
3	6A-12	L17	J30
3	GNDIO3	GND	GND

ispMACH 51024VG Logic Signal Connections (Continued)

Bank No.	Signal	484 fpBGA	676 fpBGA
3	6A-10	K21	J29
3	6A-8	K18	K26
3	6A-6	J17	J28
3	6A-4	J19	H30
3	6A-2	J22	J27
3	6A-0	J21	H29
3	7B-0	H19	G30
3	7B-2	H20	H28
3	7B-4	H17	G29
3	7B-6	H18	F30
3	7B-8	H22	G28
3	7B-10	H21	H26
3	GNDIO3	GND	GND
3	7B-12	G20	F29
3	7B-14	G22	G27
3	7B-16	G17	E30
3	7B-18	G21	F28
3	7B-20	F19	H25
3	7B-22	F20	E29
3	7B-24	F22	D30
3	7B-26	E22	E28
3	7B-28	E19	D29
3	7B-30	E20	C30
3	7A-30	D22	F26
3	7A-28	D21	E27
3	GNDIO3	GND	GND
3	7A-26	D20	D28
3	7A-24	C22	F25
3	7A-22	C18	C29
3	7A-20	C19	B30
3	7A-18	D17	D27
3	7A-16	C21	E25
3	7A-14	NC	D26
3	7A-12	NC	C27
3	GNDIO3	GND	GND
3	7A-10	NC	B28
3	7A-8	NC	A29
3	7A-6	B22	F23
3	7A-4	D18	C26
3	7A-2	B20	B27
3	7A-0	F17	A28
3	7D-0	B19	A27
3	7D-2	C17	B26

Bank No.	Signal	484 fpBGA	676 fpBGA
3	GNDIO3	GND	GND
3	7D-4	A21	E23
3	7D-6	D15	D24
3	7D-8	A20	C25
3	7D-10	C16	A26
3	7D-12	A19	B25
3	7D-14	F16	C24
3	7D-16	B16	A25
3	7D-18	D14	B24
3	7D-20	A18	C23
3	7D-22	F15	D22
3	7D-24	A17	A24
3	7D-26	B15	E21
3	GNDIO3	GND	GND
3	7D-28	A16	B23
3	7D-30	F14	C22
3	7C-0	C15	A23
3	7C-2	D13	B22
3	7C-4	E15	C21
3	7C-6	F13	A22
3	7C-8	B14	D20
3	7C-10	E13	B21
3	7C-12/VREF3	A15	E19
3	7C-14	D12	C20
3	7C-16	A14	A21
3	7C-18	B13	B20
3	GNDIO3	GND	GND
3	7C-20	A13	A20
3	7C-22	B12	C19
3	7C-24	C13	B19
3	7C-26	A12	A19
3	7C-28	C12	B18
3	7C-30	A11	A18
—	GCLK0	P6	R5
—	GCLK1	R6	T6
—	GCLK2	P17	R25
—	GCLK3	P19	P26
—	GOE0	R18	T26
—	GOE1	R17	R26
—	RESETB	R19	T25
—	TCK	R3	U5
—	TDI	R2	T5
—	TDO	R4	V5

Signal Configuration

ispMACH 5768VG and 51024VG 484-ball fpBGA

	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	
A	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O / VREF3	I/O	I/O	I/O	I/O	I/O	I/O / VREF0	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	A
B	I/O	VCC	I/O	I/O	VCC03	VCC	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC	VCC00	I/O	I/O	VCC	I/O	B
C	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	C
D	I/O	I/O	I/O	GND	I/O	I/O	VCC03	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC00	I/O	I/O	GND	I/O	I/O	I/O	D
E	I/O	VCC03	I/O	I/O	VCC	VCC03	GND	I/O	VCC03	I/O	I/O	I/O	I/O	VCC00	I/O	GND	VCC00	VCC	I/O	I/O	VCC00	I/O	E
F	I/O	VCC	I/O	I/O	VCC03	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC00	I/O	I/O	VCC	I/O	F
G	I/O	I/O	I/O	VCC03	GND	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	GND	VCC00	I/O	I/O	I/O	G
H	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O	I/O	I/O	I/O	H
J	I/O	I/O	VCC	I/O	VCC03	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	VCC00	I/O	VCC	I/O	I/O	J
K	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O	I/O	I/O	I/O	K
L	I/O	I/O	I/O / CLK_OUT1	I/O	I/O	I/O	GNDP1	GND	GND	GND	GND	GND	GND	GND	GND	GND	VCCP0	GNDP0	I/O	I/O	I/O	I/O	L
M	I/O	I/O	I/O	I/O	I/O	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O / PLL_RST0	I/O	I/O	I/O	M
N	I/O	I/O	I/O / PLL_RST1	I/O	VCCP1	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	I/O / PLL_FBK0	I/O	I/O	I/O / CLK_OUT0	N
P	I/O	I/O / PLL_FBK1	VCC	GCLK3	VCC02	GCLK2	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GCLK0	VCC01	VCCJ	VCC	I/O	I/O	P
R	I/O	I/O	I/O	RESETB	GOE0	GOE1	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GCLK1	I/O	TDO	TCK	TDI	I/O	R
T	I/O	I/O	I/O	GND	TOE	I/O	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	I/O	I/O	GND	I/O	I/O	TMS	T
U	I/O	VCC	I/O	I/O	VCC02	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	VCC01	I/O	I/O	VCC	I/O	U
V	I/O	I/O	I/O	I/O	I/O	VCC02	I/O	I/O	VCC02	I/O	I/O	I/O	I/O	VCC01	I/O	I/O	VCC01	I/O	I/O	I/O	I/O	I/O	V
W	I/O	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	I/O	I/O	I/O	I/O	I/O	I/O	W
Y	I/O	I/O	VCC02	I/O	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O	I/O	VCC01	I/O	I/O	Y
AA	I/O	VCC	I/O	I/O	I/O	VCC	I/O	I/O	I/O	I/O / VREF2	I/O	I/O	I/O / VREF1	I/O	I/O	I/O	VCC	I/O	I/O	I/O	VCC	NC ¹	AA
AB	GND	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	I/O	GND	AB
	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	

ispMACH 5768VG and 51024VG

484BGA/51024VG

Bottom View

1. NCs are not to be connected to any active signals, VCC or GND.

Note: Ball A1 indicator dot on top side of package.

Industrial

Part Number	Package	Pin Count	Macrocells	Tpd	Voltage
LC51024VG-75F484I	fpBGA	484	1024	7.5	3.3
LC51024VG-10F484I	fpBGA	484	1024	10	3.3
LC51024VG-12F484I	fpBGA	484	1024	12	3.3
LC51024VG-75F676I	fpBGA	676	1024	7.5	3.3
LC51024VG-10F676I	fpBGA	676	1024	10	3.3
LC51024VG-12F676I	fpBGA	676	1024	12	3.3
LC5768VG-75F256I	fpBGA	256	768	7.5	3.3
LC5768VG-10F256I	fpBGA	256	768	10	3.3
LC5768VG-12F256I	fpBGA	256	768	12	3.3
LC5768VG-75F484I	fpBGA	484	768	7.5	3.3
LC5768VG-10F484I	fpBGA	484	768	10	3.3
LC5768VG-12F484I	fpBGA	484	768	12	3.3

Note: the ispMACH 5000VG family is dual-marked with both Commercial and Industrial grades. The Commercial speed grade is one speed grade faster (i.e. LC51024VG-75F484C) than the Industrial speed grade (i.e. LC51024VG-10F484I).

For Further Information

In addition to this data sheet, the following technical notes may be helpful when designing with the ispMACH 5000VG family:

- *ispMACH 5000VG sysIO Design and Usage Guidelines* (TN1000)
- *ispMACH 5000VG Timing Model Design and Usage Guidelines* (TN1001)
- *Power Estimation in ispMACH 5000VG Devices* (TN1002)
- *ispMACH 5000VG PLL Usage Guidelines* (TN1003)